



european society for precision engineering and nanotechnology

European Society for Precision Engineering & Nanotechnology (euspen)

Advance the arts, sciences and technology of precision engineering, micro-engineering and nanotechnology



In 1998 objective of **euspen** was to promote:

- The industrial competitiveness of EU companies in High Precision Engineering (HPE) and nano-engineering
- To build up a strong international membership (industrial and academic) creating harmonious relationships
- To become financially self-supporting
- To enthuse young, high calibre engineers
- To establish a strong, expert community based on co-operation, friendship and enthusiasm
- To run successful events

Defined mission:

- Advance the arts, sciences and technology of precision engineering, micro engineering and nanotechnology
- Promote its dissemination through education and training
- Facilitate its exploitation through science and industry

Annual International Conference & Exhibition with Special Interest Group (SIG) meetings held every two years

The event structure includes keynotes, oral and poster contributions, tutorials and workshops (including project dissemination)

International conference: ~350-400 delegates; 40 exhibitors

Lamdap conference : ~80-100

SIG meetings: ~65-80

Number of members: ~745 (inc. students and associated members)

SIG Micro/Nano Manufacturing | SIG Precision Motion Systems & Control | Lamdap conference
SIG Sustainable Energy Systems | SIG Thermal Issues

The Society has a stable governance structure:
 12 council members have a three-year tenure; XB complete a two-year term

Dr. Hélène Mainaud Durand CERN, CH President	Prof. Richard Leach University of Nottingham, UK Vice President
Prof. Enrico Savio University of Padova, IT Immediate Past President	Prof. Dr. Andreas Archenti KTH Royal Institute of Technology, SE
Prof. Liam Blunt University of Huddersfield, UK	Dr. Jelm Franse ASML, NL
Dr. Anke Günther Reishauer AG, CH	Mr Thomas Ittner Carl Zeiss AG, DE
Dr. Geoff McFarland Renishaw plc, UK	Dr. Oltmann Riemer University of Bremen (LFM), DE
Dr. Ir. Theo A.M. Ruijl MI-Partners BV, NL	Prof. Guido Tosello Technical University of Denmark (DTU), DK

President 2021-2023

Dr. Hélène Mainaud Durand
 CERN, CH



The needs of the Society are matched by the experienced and motivated persons based at **euspen** HQ:

Dishi Phillips, Executive Director

Clare Nisbet, Projects Co-ordinator

David Billington, Consultant/Director (part-time)

Louise Tilbury, Book-Keeper (part time - 1 day per week)





- **euspen** was successful in obtaining the funding grant for the application submitted in 2019 (Erasmus + VET KA2)
- Project partners: DSPE (NL), DGaO (DE), KU Leuven (BE), Technical University of Denmark (DK), University of Huddersfield (UK), University of Padova (IT)
- Project name: PREFAM - European framework for continuous professional development in precision engineering for advanced manufacturing
- Project timescale: September 2019 – August 2022

Education Programme ECP²

Co-funded by the
Erasmus+ Programme
of the European Union



The key objectives of the PREFAM project are by 2022

- Fully develop a European framework for training in PE for Advanced Manufacturing, to increase the availability of specialised trainings in multiple European countries
- Define a strategy and guidelines for learning success design and evaluation
- Develop procedures for course management and monitoring in a European dimension
- Produce Good practice guides for new courses development, including soft-skills, hands-on activities and innovative teaching styles
- Design, develop and validate new courses based on market requirements
- Monitor new training opportunities and new needs for precision engineers

- SIG: Advancing Precision in Additive Manufacturing, St. Gallen, Switzerland: 20-22 September 2021
- SIG: Sustainable Energy Systems, PTB, Braunschweig, Germany: 13-14 October 2021
- SIG: Micro/Nano Manufacturing, Styria, Austria: 17-18 November 2021

- SIG: Thermal Issues, March 2022

Returning to Geneva...

- **euspen 22nd** International Conference & Exhibition, CERN, CH: **30 May-3 June 2022**

Returning to Technical University of Denmark...

- **euspen 23rd** International Conference & Exhibition, Copenhagen, DK: **12-16 June 2023**

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